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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, FlexIO, SPI, UART/USART
Peripherals	DMA, I²S, PWM, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 15x16b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	36-XFBGA
Supplier Device Package	36-XFBGA (3.5x3.5)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mkl17z32vda4

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2.1.1 ARM Cortex-M0+ core

The enhanced ARM Cortex M0+ is the member of the Cortex-M series of processors targeting microcontroller cores focused on very cost sensitive, low power applications. It has a single 32-bit AMBA AHB-Lite interface and includes an NVIC component. It also has hardware debug functionality including support for simple program trace capability. The processor supports the ARMv6-M instruction set (Thumb) architecture including all but three 16-bit Thumb opcodes (52 total) plus seven 32-bit instructions. It is upward compatible with other Cortex-M profile processors.

2.1.2 NVIC

The Nested Vectored Interrupt Controller supports nested interrupts and 4 priority levels for interrupts. In the NVIC, each source in the IPR registers contains two bits. It also differs in number of interrupt sources and supports 32 interrupt vectors.

The Cortex-M family uses a number of methods to improve interrupt latency to up to 15 clock cycles for Cortex-M0+. It also can be used to wake the MCU core from Wait and VLPW modes.

2.1.3 AWIC

The asynchronous wake-up interrupt controller (AWIC) is used to detect asynchronous wake-up events in Stop mode and signal to clock control logic to resume system clocking. After clock restarts, the NVIC observes the pending interrupt and performs the normal interrupt or event processing. The AWIC can be used to wake MCU core from Stop and VLPS modes.

Wake-up sources are listed as below:

Table 2. AWIC stop wake-up sources

Wake-up source	Description
Available system resets	$\overline{\text{RESET}}$ pin with filter mode disabled or enabled when LPO is its clock source, COP when its clock source is enabled. COP can also work when its clock source is enabled during Stop mode.
Low-voltage detect	Power management controller—functional in Stop mode
Low-voltage warning	Power management controller—functional in Stop mode
Pin interrupts	Port control module—any enabled pin interrupt is capable of waking the system
ADC	The ADC is functional when using internal clock source or external crystal clock
CMP0	Interrupt in normal or trigger mode

Table continues on the next page...

Table 4. Module clocks

Module	Bus interface clock	Internal clocks	I/O interface clocks
Core modules			
ARM Cortex-M0+ core	Platform clock	Core clock	—
NVIC	Platform clock	—	—
DAP	Platform clock	—	SWD_CLK
System modules			
DMA	System clock	—	—
DMA Mux	Bus clock	—	—
Port control	Bus clock	—	—
Crossbar Switch	Platform clock	—	—
Peripheral bridges	System clock	Bus clock	—
LLWU, PMC, SIM, RCM	Bus clock	LPO	—
Mode controller	Bus clock	—	—
MCM	Platform clock	—	—
COP watchdog	Bus clock	LPO, Bus Clock, MCGIRCLK, OSCERCLK	—
CRC	Bus clock	—	—
Clocks			
MCG_Lite	Bus clock	MCGOUTCLK, MCGPCLK, MCGIRCLK, OSCERCLK, ERCLK32K	—
OSC	Bus clock	OSCERCLK	—
Memory and memory interfaces			
Flash Controller	Platform clock	Flash clock	—
Flash memory	Flash clock	—	—
Analog			
ADC	Bus clock	OSCERCLK	—
CMP	Bus clock	—	—
Internal Voltage Reference (VREF)	Bus clock	—	—
Timers			
TPM	Bus clock	TPM clock	TPM_CLKIN0, TPM_CLKIN1
PIT	Bus clock	—	—
LPTMR	Bus clock	LPO, OSCERCLK, MCGPCLK, ERCLK32K	—
RTC	Bus clock	ERCLK32K	RTC_CLKOUT, RTC_CLKIN
Communication interfaces			
SPI0	Bus clock	—	SPI0_SCK
SPI1	System clock	—	SPI1_SCK
I^2C0	System Clock	—	I2C0_SCL

Table continues on the next page...

- 16-bit prescaler with compensation that can correct errors between 0.12 ppm and 3906 ppm
- Register write protection with register lock mechanism
- 1 Hz square wave or second pulse output with optional interrupt

2.2.8 PIT

The Periodic Interrupt Timer (PIT) is used to generate periodic interrupt to the CPU. It has two independent channels and each channel has a 32-bit counter. Both channels can be chained together to form a 64-bit counter.

Channel 0 can be used to periodically trigger DMA channel 0, and channel 1 can be used to periodically trigger DMA channel 1. Either channel can be programmed as an ADC trigger source, or TPM trigger source. Channel 0 can be programmed to trigger DAC.

The PIT module has the following features:
- Each 32-bit timers is able to generate DMA trigger
- Each 32-bit timers is able to generate timeout interrupts
- Two timers can be cascaded to form a 64-bit timer
- Each timer can be programmed as ADC/TPM trigger source
- Timer 0 is able to trigger DAC

2.2.9 LPTMR

The low-power timer (LPTMR) can be configured to operate as a time counter with optional prescaler, or as a pulse counter with optional glitch filter, across all power modes, including the low-leakage modes. It can also continue operating through most system reset events, allowing it to be used as a time of day counter.

The LPTMR module has the following features:
- 16-bit time counter or pulse counter with compare
  - Optional interrupt can generate asynchronous wakeup from any low-power mode
  - Hardware trigger output
  - Counter supports free-running mode or reset on compare
- Configurable clock source for prescaler/glitch filter
- Configurable input source for pulse counter

- Full-duplex or single-wire bidirectional mode
- Programmable transmit bit rate
- Double-buffered transmit and receive data register
- Serial clock phase and polarity options
- Slave select output
- Mode fault error flag with CPU interrupt capability
- Control of SPI operation during wait mode
- Selectable MSB-first or LSB-first shifting
- Programmable 8- or 16-bit data transmission length
- Receive data buffer hardware match feature
- 64-bit FIFO mode for high speed/large amounts of data transfers
- Support DMA

2.2.14 I2C

This device contains two I2C modules, which support up to 1 Mbits/s by dual buffer features, and address match to wake MCU from the low power mode.

I2C modules support DMA transfer, and the interrupt condition can trigger DMA request when DMA function is enabled.

The I2C modules have the following features:

- Support for system management bus (SMBus) Specification, version 2
- Software programmable for one of 64 different serial clock frequencies
- Software-selectable acknowledge bit
- Arbitration-lost interrupt with automatic mode switching from master to slave
- Calling address identification interrupt
- START and STOP signal generation and detection
- Repeated START signal generation and detection
- Acknowledge bit generation and detection
- Bus busy detection
- General call recognition
- 10-bit address extension
- Programmable input glitch filter
- Low power mode wakeup on slave address match
- Range slave address support
- DMA support
- Double buffering support to achieve higher baud rate

2.2.15 FlexIO

The FlexIO is a highly configurable module providing a wide range of protocols including, but not limited to UART, I2C, SPI, I2S, Camera IF, LCD RGB, PWM/ Waveform generation. The module supports programmable baud rates independent of bus clock frequency, with automatic start/stop bit generation.

The FlexIO module has the following features:

- Functional in VLPR/VLPW/Stop/VLPS mode provided the clock it is using remains enabled
- Four 32-bit double buffered shift registers with transmit, receive, and data match modes, and continuous data transfer
- The timing of the shifter' shift, load and store events are controlled by the highly flexible 16-bit timer assigned to the shifter
- Two or more shifter can be concatenated to support large data transfer sizes
- Each 16-bit timers operates independently, supports for reset, enable and disable on a variety of internal or external trigger conditions with programmable trigger polarity
- Flexible pin configuration supporting output disabled, open drain, bidirectional output data and output mode
- Supports interrupt, DMA or polled transmit/receive operation

2.2.16 Port control and GPIO

The Port Control and Interrupt (PORT) module provides support for port control, digital filtering, and external interrupt functions. The GPIO data direction and output data registers control the direction and output data of each pin when the pin is configured for the GPIO function. The GPIO input data register displays the logic value on each pin when the pin is configured for any digital function, provided the corresponding Port Control and Interrupt module for that pin is enabled.

The following figure shows the basic I/O pad structure. This diagram applies to all I/O pins except PTA20/RESET_b and those configured as pseudo open-drain outputs. PTA20/RESET_b is a true open-drain pin without p-channel output driver or diode to the ESD bus. Pseudo open-drain pins have the p-channel output driver disabled when configured for open-drain operation. None of the I/O pins, including open-drain and pseudo open-drain pins, are allowed to go above VDD.

64 LQFP	36 XFBGA	32 QFN	48 QFN	64 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
						ADC0_ SE4a	ADC0_ SE4a							
11	E1	—	—	G2	PTE22	ADC0_DP3/ ADC0_SE3	ADC0_DP3/ ADC0_SE3	PTE22		TPM2_CH0	UART2_TX		FXIO0_D6	
12	F1	—	—	F2	PTE23	ADC0_ DM3/ ADC0_ SE7a	ADC0_ DM3/ ADC0_ SE7a	PTE23		TPM2_CH1	UART2_RX		FXIO0_D7	
13	D3	7	9	F4	VDDA	VDDA	VDDA							
14	D3	7	10	G4	VREFH	VREFH	VREFH							
14	—	—	10	G4	VREFO	VREFO_A	VREFO_A							
15	D4	8	11	G3	VREFL	VREFL	VREFL							
16	D4	8	12	F3	VSSA	VSSA	VSSA							
17	—	—	13	H1	PTE29	CMP0_IN5/ ADC0_ SE4b	CMP0_IN5/ ADC0_ SE4b	PTE29		TPM0_CH2	TPM_ CLKIN0			
18	F2	9	14	H2	PTE30	ADC0_ SE23/ CMP0_IN4	ADC0_ SE23/ CMP0_IN4	PTE30		TPM0_CH3	TPM_ CLKIN1	LPUART1_ TX	LPTMR0_ ALT1	
19	—	—	—	H3	PTE31	DISABLED		PTE31		TPM0_CH4				
20	—	—	15	H4	PTE24	DISABLED		PTE24		TPM0_CH0		I2C0_SCL		
21	—	—	16	H5	PTE25	DISABLED		PTE25		TPM0_CH1		I2C0_SDA		
22	F3	10	17	D3	PTA0	SWD_CLK		PTA0		TPM0_CH5				SWD_CLK
23	F4	11	18	D4	PTA1	DISABLED		PTA1	LPUART0_ RX	TPM2_CH0				
24	E4	12	19	E5	PTA2	DISABLED		PTA2	LPUART0_ TX	TPM2_CH1				
25	E5	13	20	D5	PTA3	SWD_DIO		PTA3	I2C1_SCL	TPM0_CH0				SWD_DIO
26	F5	14	21	G5	PTA4	NMI_b		PTA4	I2C1_SDA	TPM0_CH1				NMI_b
27	—	—	—	F5	PTA5	DISABLED		PTA5		TPM0_CH2				
28	—	—	—	H6	PTA12	DISABLED		PTA12		TPM1_CH0				
29	—	—	—	G6	PTA13	DISABLED		PTA13		TPM1_CH1				
30	C3	15	22	G7	VDD	VDD	VDD							
31	C4	16	23	H7	VSS	VSS	VSS							
32	F6	17	24	H8	PTA18	EXTAL0	EXTAL0	PTA18		LPUART1_ RX	TPM_ CLKIN0			
33	E6	18	25	G8	PTA19	XTAL0	XTAL0	PTA19		LPUART1_ TX	TPM_ CLKIN1		LPTMR0_ ALT1	
34	D5	19	26	F8	PTA20	RESET_b		PTA20						RESET_b
35	D6	20	27	F7	PTB0/ LLWU_P5	ADC0_SE8	ADC0_SE8	PTB0/ LLWU_P5	I2C0_SCL	TPM1_CH0	SPI1_MOSI	SPI1_MISO		
36	C6	21	28	F6	PTB1	ADC0_SE9	ADC0_SE9	PTB1	I2C0_SDA	TPM1_CH1	SPI1_MISO	SPI1_MOSI		

64 LQFP	36 XFBGA	32 QFN	48 QFN	64 MAPBGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
37	—	—	29	E7	PTB2	ADC0_SE12	ADC0_SE12	PTB2	I2C0_SCL	TPM2_CH0				
38	—	—	30	E8	PTB3	ADC0_SE13	ADC0_SE13	PTB3	I2C0_SDA	TPM2_CH1				
39	—	—	31	E6	PTB16	DISABLED		PTB16	SPI1_MOSI	LPUART0_RX	TPM_CLKIN0	SPI1_MISO		
40	—	—	32	D7	PTB17	DISABLED		PTB17	SPI1_MISO	LPUART0_TX	TPM_CLKIN1	SPI1_MOSI		
41	—	—	—	D6	PTB18	DISABLED		PTB18		TPM2_CH0				
42	—	—	—	C7	PTB19	DISABLED		PTB19		TPM2_CH1				
43	—	—	33	D8	PTC0	ADC0_SE14	ADC0_SE14	PTC0		EXTRG_IN		CMP0_OUT		
44	C5	22	34	C6	PTC1/LLWU_P6/RTC_CLKIN	ADC0_SE15	ADC0_SE15	PTC1/LLWU_P6/RTC_CLKIN	I2C1_SCL		TPM0_CH0			
45	B6	23	35	B7	PTC2	ADC0_SE11	ADC0_SE11	PTC2	I2C1_SDA		TPM0_CH1			
46	B5	24	36	C8	PTC3/LLWU_P7	DISABLED		PTC3/LLWU_P7	SPI1_SCK	LPUART1_RX	TPM0_CH2	CLKOUT		
47	—	—	—	E3	VSS	VSS	VSS							
48	—	—	—	E4	VDD	VDD	VDD							
49	A6	25	37	B8	PTC4/LLWU_P8	DISABLED		PTC4/LLWU_P8	SPI0_PCS0	LPUART1_TX	TPM0_CH3	SPI1_PCS0		
50	A5	26	38	A8	PTC5/LLWU_P9	DISABLED		PTC5/LLWU_P9	SPI0_SCK	LPTMR0_ALT2			CMP0_OUT	
51	B4	27	39	A7	PTC6/LLWU_P10	CMP0_IN0	CMP0_IN0	PTC6/LLWU_P10	SPI0_MOSI	EXTRG_IN		SPI0_MISO		
52	A4	28	40	B6	PTC7	CMP0_IN1	CMP0_IN1	PTC7	SPI0_MISO			SPI0_MOSI		
53	—	—	—	A6	PTC8	CMP0_IN2	CMP0_IN2	PTC8	I2C0_SCL	TPM0_CH4				
54	—	—	—	B5	PTC9	CMP0_IN3	CMP0_IN3	PTC9	I2C0_SDA	TPM0_CH5				
55	—	—	—	B4	PTC10	DISABLED		PTC10	I2C1_SCL					
56	—	—	—	A5	PTC11	DISABLED		PTC11	I2C1_SDA					
57	—	—	41	C3	PTD0	DISABLED		PTD0	SPI0_PCS0		TPM0_CH0		FXIO0_D0	
58	—	—	42	A4	PTD1	ADC0_SE5b	ADC0_SE5b	PTD1	SPI0_SCK		TPM0_CH1		FXIO0_D1	
59	—	—	43	C2	PTD2	DISABLED		PTD2	SPI0_MOSI	UART2_RX	TPM0_CH2	SPI0_MISO	FXIO0_D2	
60	—	—	44	B3	PTD3	DISABLED		PTD3	SPI0_MISO	UART2_TX	TPM0_CH3	SPI0_MOSI	FXIO0_D3	
61	A3	29	45	A3	PTD4/LLWU_P14	DISABLED		PTD4/LLWU_P14	SPI1_PCS0	UART2_RX	TPM0_CH4		FXIO0_D4	
62	B3	30	46	C1	PTD5	ADC0_SE6b	ADC0_SE6b	PTD5	SPI1_SCK	UART2_TX	TPM0_CH5		FXIO0_D5	
63	B2	31	47	B2	PTD6/LLWU_P15	ADC0_SE7b	ADC0_SE7b	PTD6/LLWU_P15	SPI1_MOSI	LPUART0_RX	I2C1_SDA	SPI1_MISO	FXIO0_D6	

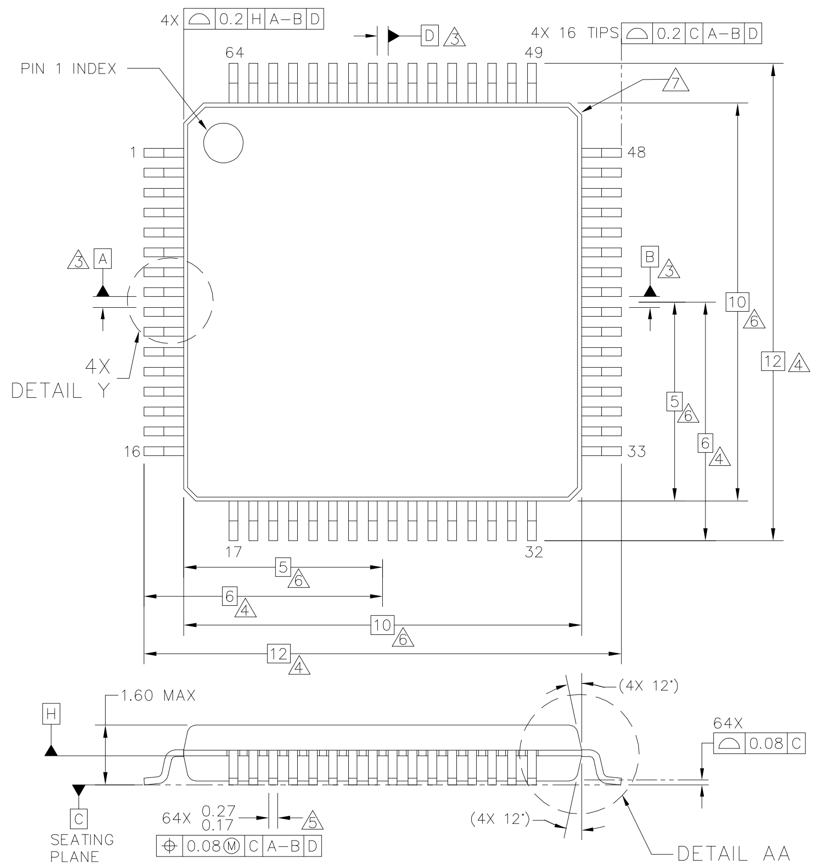

Figure 11. 64-pin LQFP package dimensions 1

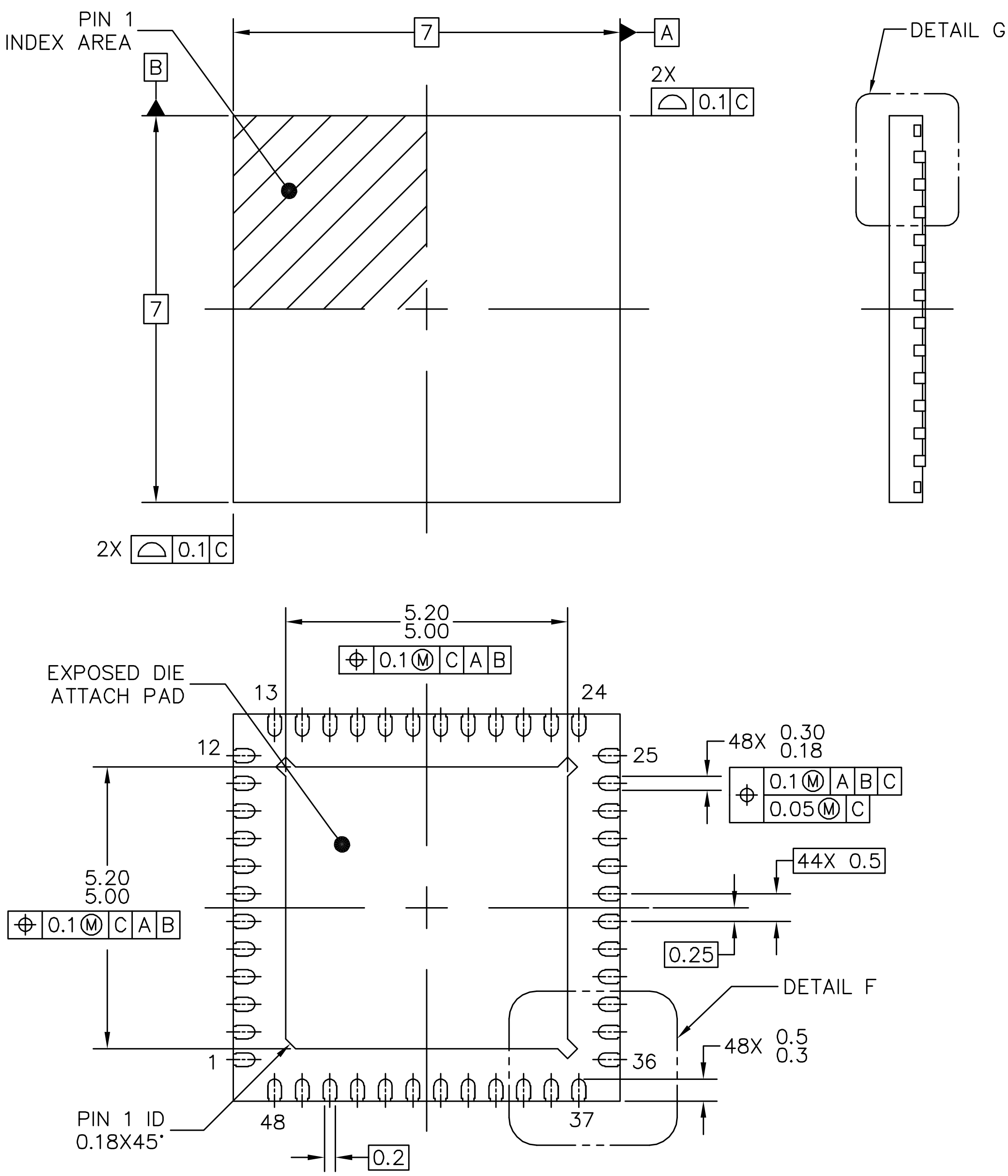

Figure 14. 48-pin QFN package dimension 1

5.1.1 Thermal handling ratings

Table 30. Thermal handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
T_{STG}	Storage temperature	–55	150	°C	1
T_{SDR}	Solder temperature, lead-free	—	260	°C	2

1. Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
2. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

5.1.2 Moisture handling ratings

Table 31. Moisture handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
MSL	Moisture sensitivity level	—	3	—	1

1. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

5.1.3 ESD handling ratings

Table 32. ESD handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
V_{HBM}	Electrostatic discharge voltage, human body model	–2000	+2000	V	1
V_{CDM}	Electrostatic discharge voltage, charged-device model	–500	+500	V	2
I_{LAT}	Latch-up current at ambient temperature of 105 °C	–100	+100	mA	3

1. Determined according to JEDEC Standard JESD22-A114, *Electrostatic Discharge (ESD) Sensitivity Testing Human Body Model (HBM)*.
2. Determined according to JEDEC Standard JESD22-C101, *Field-Induced Charged-Device Model Test Method for Electrostatic-Discharge-Withstand Thresholds of Microelectronic Components*.
3. Determined according to JEDEC Standard JESD78, *IC Latch-Up Test*.

5.1.4 Voltage and current absolute operating ratings

Table 33. Voltage and current absolute operating ratings

Symbol	Description	Min.	Max.	Unit
V_{DD}	Digital supply voltage	–0.3	3.8	V
I_{DD}	Digital supply current	—	120	mA

Table continues on the next page...

Table 35. V_{DD} supply LVD and POR operating requirements (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
V_{LVW4H}	• Level 3 falling (LVWV = 10) • Level 4 falling (LVWV = 11)	2.92	3.00	3.08	V	
V_{HYSH}	Low-voltage inhibit reset/recover hysteresis — high range	—	±60	—	mV	—
V_{LVDL}	Falling low-voltage detect threshold — low range (LVDV=00)	1.54	1.60	1.66	V	—
	Low-voltage warning thresholds — low range					1
V_{LVW1L}	• Level 1 falling (LVWV = 00)	1.74	1.80	1.86	V	
V_{LVW2L}	• Level 2 falling (LVWV = 01)	1.84	1.90	1.96	V	
V_{LVW3L}	• Level 3 falling (LVWV = 10)	1.94	2.00	2.06	V	
V_{LVW4L}	• Level 4 falling (LVWV = 11)	2.04	2.10	2.16	V	
V_{HYSL}	Low-voltage inhibit reset/recover hysteresis — low range	—	±40	—	mV	—
V_{BG}	Bandgap voltage reference	0.97	1.00	1.03	V	—
t_{LPO}	Internal low power oscillator period — factory trimmed	900	1000	1100	μs	—

1. Rising thresholds are falling threshold + hysteresis voltage

5.2.2.3 Voltage and current operating behaviors

Table 36. Voltage and current operating behaviors

Symbol	Description	Min.	Max.	Unit	Notes
V_{OH}	Output high voltage — normal drive pad				1
	• 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = –5 mA	V_{DD} – 0.5	—	V	
	• 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = –2.5 mA	V_{DD} – 0.5	—	V	
V_{OH}	Output high voltage — high drive pad				1
	• 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OH} = –20 mA	V_{DD} – 0.5	—	V	
	• 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OH} = –10 mA	V_{DD} – 0.5	—	V	
I_{OHT}	Output high current total for all ports	—	100	mA	
V_{OL}	Output low voltage — normal drive pad				1
	• 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 5 mA	—	0.5	V	
	• 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 2.5 mA	—	0.5	V	
V_{OL}	Output low voltage — high drive pad				1
	• 2.7 V ≤ V_{DD} ≤ 3.6 V, I_{OL} = 20 mA	—	0.5	V	
	• 1.71 V ≤ V_{DD} ≤ 2.7 V, I_{OL} = 10 mA	—	0.5	V	
I_{OLT}	Output low current total for all ports	—	100	mA	

Table continues on the next page...

Table 38. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I_{DD_VLPS}	Very-low-power stop mode current at 3.0 V • at 25 °C and below • at 50 °C • at 85 °C • at 105 °C	— — — —	2.34 5.04 20.48 42.34	3.80 8.03 31.97 65.78	µA	
I_{DD_VLPS}	Very-low-power stop mode current at 1.8 V • at 25 °C and below • at 50 °C • at 85 °C • at 105 °C	— — — —	2.33 4.95 20.18 41.93	3.80 7.94 31.57 65.17	µA	
I_{DD_LLS}	Low-leakage stop mode current, all peripheral disable, at 3.0 V • at 25 °C and below • at 50 °C • at 70 °C • at 85 °C • at 105 °C	— — — — —	1.71 2.59 4.46 7.55 17.03	1.96 3.30 7.06 10.15 22.67	µA	
I_{DD_LLS}	Low-leakage stop mode current with RTC current, at 3.0 V • at 25 °C and below • at 50 °C • at 70 °C • at 85 °C • at 105 °C	— — — — —	2.27 3.1 4.99 8.1 17.32	2.52 3.81 7.59 10.70 22.96	µA	3
I_{DD_LLS}	Low-leakage stop mode current with RTC current, at 1.8 V • at 25 °C and below • at 50 °C • at 70 °C • at 85 °C • at 105 °C	— — — — —	2.1 2.89 4.65 7.61 16.38	2.35 3.60 7.25 10.21 22.02	µA	3
I_{DD_VLLS3}	Very-low-leakage stop mode 3 current, all peripheral disable, at 3.0 V • at 25 °C and below • at 50 °C • at 70 °C	— — — — —	1.43 2.06 3.51 5.91 13.36	1.58 2.52 5.20 7.60 17.08	µA	

Table continues on the next page...

5.3.3.2.2 Oscillator frequency specifications

Table 49. Oscillator frequency specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
f_{osc_lo}	Oscillator crystal or resonator frequency — low-frequency mode (MCG_C2[RANGE]=00)	32	—	40	kHz	
$f_{osc\_hi\_1}$	Oscillator crystal or resonator frequency — high-frequency mode (low range) (MCG_C2[RANGE]=01)	3	—	8	MHz	
$f_{osc\_hi\_2}$	Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x)	8	—	32	MHz	
f_{ec_extal}	Input clock frequency (external clock mode)	—	—	48	MHz	1, 2
t_{dc_extal}	Input clock duty cycle (external clock mode)	40	50	60	%	
t_{cst}	Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0)	—	750	—	ms	3, 4
	Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1)	—	250	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0)	—	0.6	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1)	—	1	—	ms	

1. Other frequency limits may apply when external clock is being used as a reference for the FLL
2. When transitioning from FEI or FBI to FBE mode, restrict the frequency of the input clock so that, when it is divided by FRDIV, it remains within the limits of the DCO input clock frequency.
3. Proper PC board layout procedures must be followed to achieve specifications.
4. Crystal startup time is defined as the time between the oscillator being enabled and the OSCINIT bit in the MCG_S register being set.

5.3.4 Memories and memory interfaces

5.3.4.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

5.3.4.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

Table 50. NVM program/erase timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{hvpgm4}	Longword Program high-voltage time	—	7.5	18	μs	—
$t_{hversscr}$	Sector Erase high-voltage time	—	13	113	ms	1
$t_{hversall}$	Erase All high-voltage time	—	52	452	ms	1

1. Maximum time based on expectations at cycling end-of-life.

5.3.4.1.2 Flash timing specifications — commands

Table 51. Flash command timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{rd1sec1k}$	Read 1s Section execution time (flash sector)	—	—	60	μs	1
t_{pgmchk}	Program Check execution time	—	—	45	μs	1
t_{rdrsrc}	Read Resource execution time	—	—	30	μs	1
t_{pgm4}	Program Longword execution time	—	65	145	μs	—
t_{ersscr}	Erase Flash Sector execution time	—	14	114	ms	2
t_{rd1all}	Read 1s All Blocks execution time	—	—	0.9	ms	1
t_{rdonce}	Read Once execution time	—	—	25	μs	1
$t_{pgmonce}$	Program Once execution time	—	65	—	μs	—
t_{ersall}	Erase All Blocks execution time	—	70	575	ms	2
t_{vfykey}	Verify Backdoor Access Key execution time	—	—	30	μs	1
$t_{ersallu}$	Erase All Blocks Unsecure execution time	—	70	575	ms	2

1. Assumes 25 MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.

5.3.4.1.3 Flash high voltage current behaviors

Table 52. Flash high voltage current behaviors

Symbol	Description	Min.	Typ.	Max.	Unit
I_{DD_PGM}	Average current adder during high voltage flash programming operation	—	2.5	6.0	mA
I_{DD_ERS}	Average current adder during high voltage flash erase operation	—	1.5	4.0	mA

5.3.4.1.4 Reliability specifications

Table 53. NVM reliability specifications

Symbol	Description	Min.	Typ.[1]	Max.	Unit	Notes
			Program Flash			

Table continues on the next page...

All timing is shown with respect to 20% V_{DD} and 80% V_{DD} thresholds, unless noted, as well as input signal transitions of 3 ns and a 30 pF maximum load on all SPI pins.

Table 60. SPI master mode timing on slew rate disabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	f_{periph}/2048	f_{periph}/2	Hz	1
2	t_{SPSCK}	SPSCK period	2 x t_{periph}	2048 x t_{periph}	ns	2
3	t_{Lead}	Enable lead time	1/2	—	t_{SPSCK}	—
4	t_{Lag}	Enable lag time	1/2	—	t_{SPSCK}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	t_{periph} - 30	1024 x t_{periph}	ns	—
6	t_{SU}	Data setup time (inputs)	18	—	ns	—
7	t_{HI}	Data hold time (inputs)	0	—	ns	—
8	t_v	Data valid (after SPSCK edge)	—	15	ns	—
9	t_{HO}	Data hold time (outputs)	0	—	ns	—
10	t_{RI}	Rise time input	—	t_{periph} - 25	ns	—
	t_{FI}	Fall time input				
11	t_{RO}	Rise time output	—	25	ns	—
	t_{FO}	Fall time output				

1. For SPI0 f_{periph} is the bus clock (f_{BUS}). For SPI1 f_{periph} is the system clock (f_{SYS}).
2. $t_{periph} = 1/f_{periph}$

Table 61. SPI master mode timing on slew rate enabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	f_{periph}/2048	f_{periph}/2	Hz	1
2	t_{SPSCK}	SPSCK period	2 x t_{periph}	2048 x t_{periph}	ns	2
3	t_{Lead}	Enable lead time	1/2	—	t_{SPSCK}	—
4	t_{Lag}	Enable lag time	1/2	—	t_{SPSCK}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	t_{periph} - 30	1024 x t_{periph}	ns	—
6	t_{SU}	Data setup time (inputs)	96	—	ns	—
7	t_{HI}	Data hold time (inputs)	0	—	ns	—
8	t_v	Data valid (after SPSCK edge)	—	52	ns	—
9	t_{HO}	Data hold time (outputs)	0	—	ns	—
10	t_{RI}	Rise time input	—	t_{periph} - 25	ns	—
	t_{FI}	Fall time input				
11	t_{RO}	Rise time output	—	36	ns	—
	t_{FO}	Fall time output				

1. For SPI0 f_{periph} is the bus clock (f_{BUS}). For SPI1 f_{periph} is the system clock (f_{SYS}).
2. $t_{periph} = 1/f_{periph}$

Table 62. SPI slave mode timing on slew rate disabled pads (continued)

Num.	Symbol	Description	Min.	Max.	Unit	Note
4	t_{Lag}	Enable lag time	1	—	t_{periph}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	t_{periph} - 30	—	ns	—
6	t_{SU}	Data setup time (inputs)	2.5	—	ns	—
7	t_{HI}	Data hold time (inputs)	3.5	—	ns	—
8	t_a	Slave access time	—	t_{periph}	ns	3
9	t_{dis}	Slave MISO disable time	—	t_{periph}	ns	4
10	t_v	Data valid (after SPSCK edge)	—	31	ns	—
11	t_{HO}	Data hold time (outputs)	0	—	ns	—
12	t_{RI}	Rise time input	—	t_{periph} - 25	ns	—
	t_{FI}	Fall time input				
13	t_{RO}	Rise time output	—	25	ns	—
	t_{FO}	Fall time output				

1. For SPI0 f_{periph} is the bus clock (f_{BUS}). For SPI1 f_{periph} is the system clock (f_{SYS}).
2. $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state

Table 63. SPI slave mode timing on slew rate enabled pads

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	f_{op}	Frequency of operation	0	$f_{periph}/4$	Hz	1
2	t_{SPSCK}	SPSCK period	4 x t_{periph}	—	ns	2
3	t_{Lead}	Enable lead time	1	—	t_{periph}	—
4	t_{Lag}	Enable lag time	1	—	t_{periph}	—
5	t_{WSPSCK}	Clock (SPSCK) high or low time	t_{periph} - 30	—	ns	—
6	t_{SU}	Data setup time (inputs)	2	—	ns	—
7	t_{HI}	Data hold time (inputs)	7	—	ns	—
8	t_a	Slave access time	—	t_{periph}	ns	3
9	t_{dis}	Slave MISO disable time	—	t_{periph}	ns	4
10	t_v	Data valid (after SPSCK edge)	—	122	ns	—
11	t_{HO}	Data hold time (outputs)	0	—	ns	—
12	t_{RI}	Rise time input	—	t_{periph} - 25	ns	—
	t_{FI}	Fall time input				
13	t_{RO}	Rise time output	—	36	ns	—
	t_{FO}	Fall time output				

1. For SPI0 f_{periph} is the bus clock (f_{BUS}). For SPI1 f_{periph} is the system clock (f_{SYS}).
2. $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state

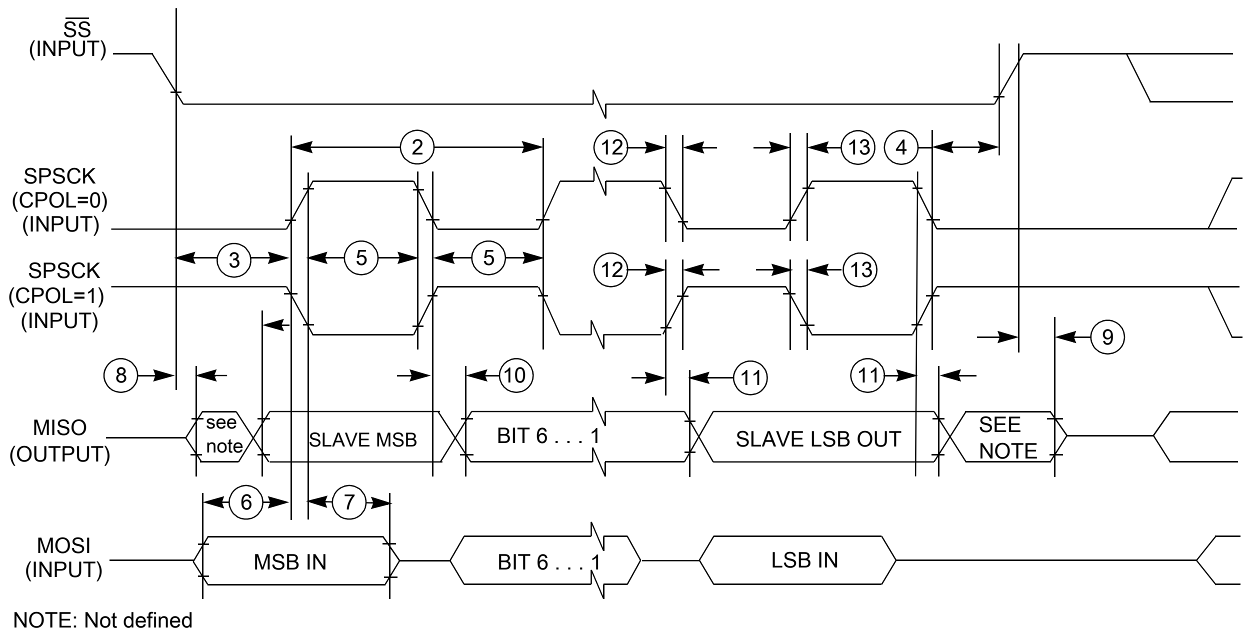

Figure 31. SPI slave mode timing (CPHA = 0)

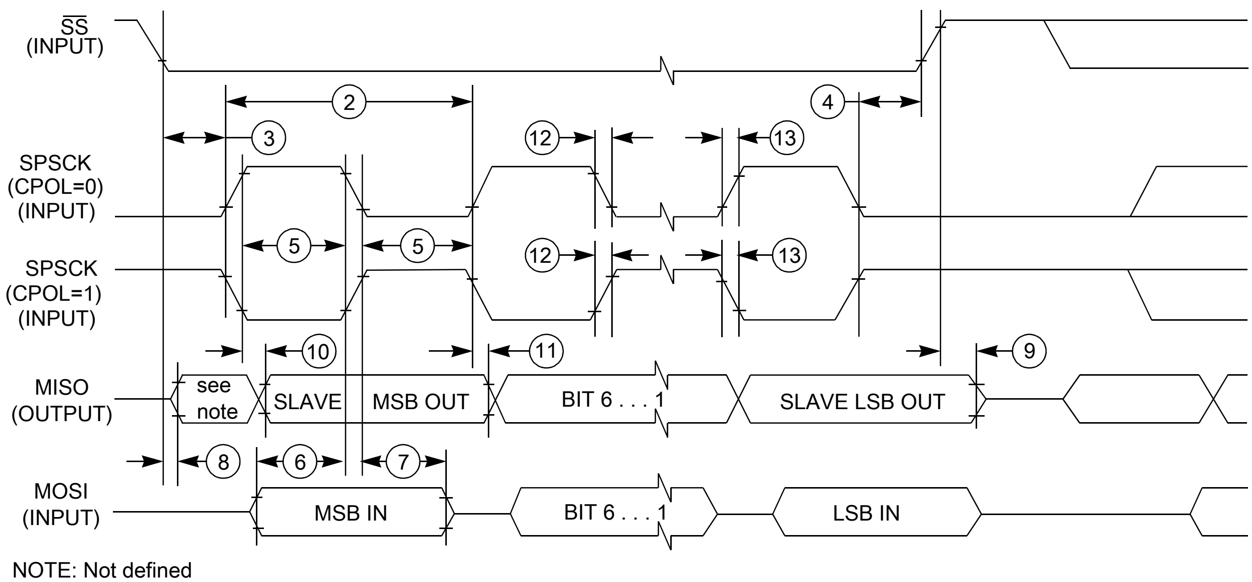

Figure 32. SPI slave mode timing (CPHA = 1)

5.5.2 Inter-Integrated Circuit Interface (I2C) timing

Table 64. I2C timing

Characteristic	Symbol	Standard Mode		Fast Mode		Unit
		Minimum	Maximum	Minimum	Maximum	
SCL Clock Frequency	f_{SCL}	0	100	0	400[1]	kHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD}; STA	4	—	0.6	—	µs
LOW period of the SCL clock	t_{LOW}	4.7	—	1.25	—	µs
HIGH period of the SCL clock	t_{HIGH}	4	—	0.6	—	µs
Set-up time for a repeated START condition	t_{SU}; STA	4.7	—	0.6	—	µs
Data hold time for I^2C bus devices	t_{HD}; DAT	0[2]	3.45[3]	0[4]	0.9[2]	µs
Data set-up time	t_{SU}; DAT	250[5]	—	100[3, 6]	—	ns
Rise time of SDA and SCL signals	t_r	—	1000	20 +0.1C_b[7]	300	ns
Fall time of SDA and SCL signals	t_f	—	300	20 +0.1C_b[6]	300	ns
Set-up time for STOP condition	t_{SU}; STO	4	—	0.6	—	µs
Bus free time between STOP and START condition	t_{BUF}	4.7	—	1.3	—	µs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	N/A	N/A	0	50	ns

1. The maximum SCL Clock Frequency in Fast mode with maximum bus loading can be achieved only when using the high drive pins across the full voltage range and when using the normal drive pins and VDD ≥ 2.7 V.
2. The master mode I^2C deasserts ACK of an address byte simultaneously with the falling edge of SCL. If no slaves acknowledge this address byte, then a negative hold time can result, depending on the edge rates of the SDA and SCL lines.
3. The maximum tHD; DAT must be met only if the device does not stretch the LOW period (tLOW) of the SCL signal.
4. Input signal Slew = 10 ns and Output Load = 50 pF
5. Set-up time in slave-transmitter mode is 1 IPBus clock period, if the TX FIFO is empty.
6. A Fast mode I^2C bus device can be used in a Standard mode I2C bus system, but the requirement $t_{SU; DAT}$ ≥ 250 ns must then be met. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, then it must output the next data bit to the SDA line $t_{rmax} + t_{SU; DAT}$ = 1000 + 250 = 1250 ns (according to the Standard mode I^2C bus specification) before the SCL line is released.
7. C_b = total capacitance of the one bus line in pF.

To achieve 1MHz I2C clock rates, consider the following recommendations:

- To counter the effects of clock stretching, the I2C baud Rate select bits can be configured for faster than desired baud rate.
- Use high drive pad and DSE bit should be set in PORTx_PCRn register.
- Minimize loading on the I2C SDA and SCL pins to ensure fastest rise times for the SCL line to avoid clock stretching.
- Use smaller pull up resistors on SDA and SCL to reduce the RC time constant.

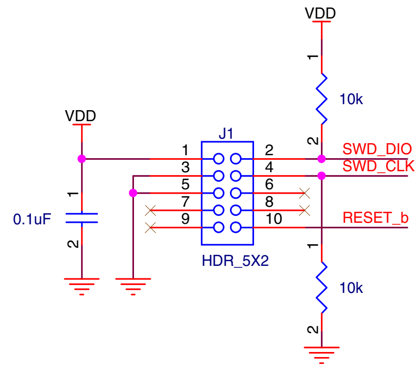

Figure 39. SWD debug interface

- Low leakage stop mode wakeup

  Select low leakage wakeup pins (LLWU_Px) to wake the MCU from one of the low leakage stop modes (LLS/VLLSx). See KL17 Signal Multiplexing and Pin Assignments for pin selection.

- Unused pin

  Unused GPIO pins must be left floating (no electrical connections) with the MUX field of the pin's PORTx_PCRn register equal to 0:0:0. This disables the digital input path to the MCU.

6.1.5 Crystal oscillator

When using an external crystal or ceramic resonator as the frequency reference for the MCU clock system, refer to the following table and diagrams.

The feedback resistor, RF, is incorporated internally with the low power oscillators. An external feedback is required when using high gain (HGO=1) mode.

The series resistor, RS, is required in high gain (HGO=1) mode when the crystal or resonator frequency is below 2MHz. Otherwise, the low power oscillator (HGO=0) must not have any series resistance; and the high frequency, high gain oscillator with a frequency above 2MHz does not require any series resistance.

Internal load capacitors (Cx, Cy) are provided in the low frequency (32.786kHz) mode. Use the SCxP bits in the OSC0_CR register to adjust the load capacitance for the crystal. Typically, values of 10pf to 16pF are sufficient for 32.768kHz crystals that have a 12.5pF CL specification. The internal load capacitor selection must not be used for high frequency crystals and resonators.